

# LCP12

### Protection IC for ringing SLICs

Datasheet – production data



### Features

- Protection IC recommended for ringing SLICs
- Wide firing voltage range: -120 V to +120 V
- Low gate triggering current: I<sub>G</sub> = 5 mA max
- Peak pulse current:  $I_{PP} = 50 \text{ A} (10/1000 \text{ } \mu\text{s})$
- Holding current: I<sub>H</sub> = 150 mA min.

### Applications

- Dual battery supply voltage SLICs
- Central office (CO)
- Private branch exchange (PBX)
- Digital loop carrier (DLC)
- Digital subscriber line access multiplexer (DSLAM)
- Fiber in the loop (FITL)
- Wireless local loop (WLL)
- Hybrid fiber coax (HFC)
- ISDN terminal adapter
- Cable modem

### Description

The LCP12 has been developed to protect SLICs operating on both negative and positive battery supplies, as well as high voltage SLICs. It provides crowbar mode protection for both TIP and RING lines. The surge suppression is assumed for each wire by two thyristor structures, one dedicated to positive surges the second one for negative surges. Both positive and negative threshold levels are programmable by two gates.

LCP12 can be used to help equipment to meet various standards such as UL1950, IEC 60950 / CSAC22.2, UL1459 and TIA-968-A. LCP12 pinout and clearance is compatible with UL60950. Resin meets UL94 V0.

LCP12 is UL497B approved - file: E136224.

The LCP12 associated with Epcos PTC model B59173C1130A151 is compliant with ITU TK20/K21 (4 kV lightning and AC power fault tests).

#### Figure 1. Functional diagram



#### Figure 2. Pin-out configuration



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This is information on a product in full production.

# 1 Characteristics

Standard	Peak surge voltage (V)	Voltage waveform	Required peak current (A)	Current waveform	Minimum series resistor Rs to meet standard ( $\Omega$ )
GR-1089 Core First level	2500 1000	2/10 µs 10/1000 µs	500 100	2/10 µs 10/1000 µs	12 10
GR-1089 Core Second level	5000	2/10 µs	500	2/10 µs	24
GR-1089 Core Intra-building	1500	2/10 µs	100	2/10 µs	0
ITU-T-K20/K21	6000 4000 1500	10/700 µs	150 100 37.5	5/310 µs	35 10 0
ITU-T-K20 (IEC61000-4-2)	8000 15000	1/60 ns	ESD contact discharge ESD air discharge		0 0
IEC61000-4-5	4000 4000	10/700 μs 1.2/50 μs	100 100	5/310 μs 8/20 μs	14 0
TIA-968-A (formerly FCC part 68) type A	1500 800	10/160 μs 10/560 μs	200 100	10/160 μs 10/560 μs	20 15
TIA-968-A (formerly FCC part 68) type B	1000	9/720 µs	25	5/320 µs	0

Table 1.	Compliant w	vith the follo	wing standards
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Table 2. Absolute maximum ratings ( $T_{amb} = 25 \text{ °C}$ )

Symbol	Parameter		Value	Unit
I <sub>PP</sub>	Peak pulse current	10/1000 μs 5/310 μs 2/10μs	50 80 150	A
I <sub>TSM</sub>	Non repetitive surge peak on-state current (F = 50 Hz) $I_{TSM}$ value specified for each line $I_{TSM}$ value can be applied on both lines at the same time (GND capability is twice the line $I_{TSM}$ )	$t_p = 0.2 \text{ s}$ $t_p = 1 \text{ s}$ $t_p = 15 \text{ min.}$	11 7.5 3	A
V <sub>Gn</sub> V <sub>Gp</sub>	Negative battery voltage range Positive battery voltage range	-120 to 0 0 to +120	V	
Тj	Operating junction temperature range	-40 to +125	°C	
T <sub>stg</sub>	Storage temperature range	-55 to +150	°C	
ΤL	Lead solder temperature (10 s duration)		260	°C



Figure 3. Pulse waveform



#### Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction to ambient	150	°C/W

#### Table 4. Parameters related to the negative suppressor

Symbol	Parameter	Test conditions	Min.	Max.	Unit
I <sub>Gn</sub>	Negative gate trigger current	V <sub>Gn/GND</sub> = -60 V Measured at 50 Hz		5	mA
I <sub>H-</sub>	Holding current (see Figure 4)	V <sub>Gn</sub> = -60 V	150		mA
		$V_{Gn/GND} = -60 V$			
V <sub>DGL-</sub>	RING <sup>(1)</sup>	10/700 $\mu$ s 2 kV R <sub>s</sub> = 25 $\Omega$ I <sub>PP</sub> = 30 A		8	V
		1.2/50 $\mu$ s 2 kV R <sub>s</sub> = 25 $\Omega$ I <sub>PP</sub> = 30 A		12	
V <sub>GnT</sub>	G <sub>n</sub> to TIP voltage	I <sub>Gn</sub> = 20 mA	0.7	1.7	V

1. The V<sub>DGL</sub> value is the difference between the peak line voltage during the surge and the programmed gate voltage.

#### Table 5. Parameters related to the positive suppressor

Symbol	Parameter	Test conditions	Min.	Max.	Unit
I <sub>Gp</sub>	Positive gate trigger current	$V_{Gp/GND}$ = 60 V, measured at 50 Hz		5	mA
V <sub>DGL+</sub>	Dynamic switching voltage Gp / TIP or RING <sup>(1)</sup>	$V_{Gp/GND} = 60 V$ 10/700 µs 2 kV R <sub>s</sub> = 25 Ω I <sub>PP</sub> = 30 A 1.2/50 µs 2 kV R <sub>s</sub> = 25 Ω I <sub>PP</sub> = 30 A		8 20	V
V <sub>GpR</sub>	G <sub>P</sub> to RING voltage	I <sub>Gp</sub> = -20 mA	1	2	V

1. The  $V_{DGL}$  value is the difference between the peak line voltage during the surge and the programmed gate voltage.

#### Table 6. Parameters related to TIP or RING / GND

Symbol	Parameter	Test conditions		Max.	Unit
I <sub>R</sub>	Reverse leakage current	$ \begin{array}{ll} V_{\text{TIP or RING}} = +120 \text{ V} & V_{\text{Gp/TIP or RING}} = +1 \text{ V} \\ V_{\text{TIP or RING}} = -120 \text{ V} & V_{\text{Gn/TIP or RING}} = -1 \text{ V} \end{array} $		5 5	μA
С	Capacitance TIP or RING / GND	$V_R$ = -3 V, F =1 MHz, $V_{Gp}$ = 60 V, $V_{Gn}$ = -60 V		60	pF



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Symbol	Component	Min.	Тур.	Max.	Unit			
C <sub>n</sub> , C <sub>p</sub>	Gate decoupling capacitance	100	220		nF			

 Table 7. Recommended gate capacitance

#### Figure 4. Relative variation of holding current versus junction temperature



Figure 5. Maximum non repetitive surge peak on state current versus overload duration



Figure 6. Capacitance versus reverse applied voltage (typical values) with V<sub>Gn</sub> = -90 V and V<sub>Gp</sub> = +90 V



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#### LCP12

### 2 Technical information



*Figure 7* shows the classical protection circuit using the LCP12 crowbar concept. This topology has been developed to protect two-battery voltage SLICs. It allows both positive and negative firing thresholds to be programmed. The LCP12 has two gates (Gn and Gp). Gn is biased to negative battery voltage -Vbat, while Gp is biased to the positive battery voltage +Vb.

When a negative surge occurs on one wire (L1 for example), a current IGn flows through the base of the transistor T1 and then injects a current in the gate of the thyristor Th1 which turns-on. All the surge current flows through the ground. After the surge, when the current flowing through Th1 becomes less negative than the negative holding current  $I_{H-}$ , Th1 switches off. This holding current  $I_{H-}$  is temperature dependent as per *Figure 4* 

When a positive surge occurs on one wire (L1 for example), a current IGp flows through the base of the transistor T2 and then injects a current in the gate of the thyristor Th2 which fires. All the surge current flows through the ground. After the surge, when the current flowing through Th2 becomes less positive than the positive holding current  $I_{H+}$ , Th2 switches off. This holding current  $I_{H+}$ , typically 20 mA at 25 °C, is temperature dependent and the same *Figure 4* also applies.

The capacitors Cn and Cp are used to speed up the crowbar structure firing during the fast rise or fall edges. This allows minimization of the dynamic breakover voltage at the SLIC TIP and RING inputs during fast surges. Please note that these capacitors are generally available around the SLIC. To be efficient they have to be as close as possible to the LCP12 gate pins (Gn and Gp) and to the reference ground track (or plan). The optimized value for Cn and Cp is 220 nF.

The series resistors Rs shown in *Figure* 7 represent the fuse resistors or the PTCs which are needed to withstand the power contact or the power induction tests imposed by the country standards. Taking this factor into account, the actual lightning surge current flowing through the LCP12 is equal to:

I surge = Vsurge / (Rg + Rs)

With

V surge = peak surge voltage imposed by the standard.

Rg = series resistor of the surge generator

Rs = series resistor of the line card (e.g. PTC)



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For a line card with 50  $\Omega$  of series resistors which has to be qualified under GR-1089 1000 V 10/1000 µs surge, the present current through the LCP12 is equal to:

The LCP12 topology is particularly optimized for the new telecom applications such as fiber in the loop, WLL systems, and decentralized central office, for example.



Figure 8. Protection of SLIC with positive and negative battery voltages

*Figure 8* shows the classical protection topology for SLIC using both positive and negative battery voltages. With such a topology the SLIC is protected against surge over +Vb and lower than -Vbat. In this case, +Vb can be programmed up to +120 V while -Vbat can be programmed down to -120 V.



### 3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.







	Dimensions						
Ref.		Millimeters		Inches			
	Min.		Max.	Min.		Max.	
А	1.70	1.90	2.10	0.07	0.07	0.08	
A1	0.05	0.10	0.25	0.00	0.00	0.01	
A2	1.65	1.80	1.75	0.06	0.07	0.07	
b	0.38	0.43	0.48	0.01	0.02	0.02	
С	0.15	0.20	0.25	0.01	0.01	0.01	
D	5.14	5.24	5.34	0.02	0.021	0.21	
Е	5.20	5.30	5.40	0.02	0.021	0.21	
E1	7.70	7.80	8.25	0.30	0.031	0.32	
е		1.27		0.05	0.05		
К			8.00	0.14	0.31		
L	0.55	0.75	0.85	0.02	0.03	0.03	

Table 8. SO-8 wide dimension values

#### Figure 10. SO-8 wide footprint in mm (inches)





# 4 Ordering information

Table	9.	Ordering	information
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Order code	Marking	Package	Weight	Base qty	Delivery mode
LCP12-150B1RL	LCP12	SO-8 wide	0.125g	1500	Tape and reel

## 5 Revision history

	Table 10.	Document	revision	historv
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Date	Revision	Changes
14-May-2010	1	Initial release.
23-Feb-2012	2	Updated dimensions in <i>Table 8</i> . Standardized nomenclature for Gn and Gp.
18-Jun-2012	3	Updated dimension D in SO-8 wide.
20-Mar-2014	4	Updated Description, Table 6 and Package information formatting.



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